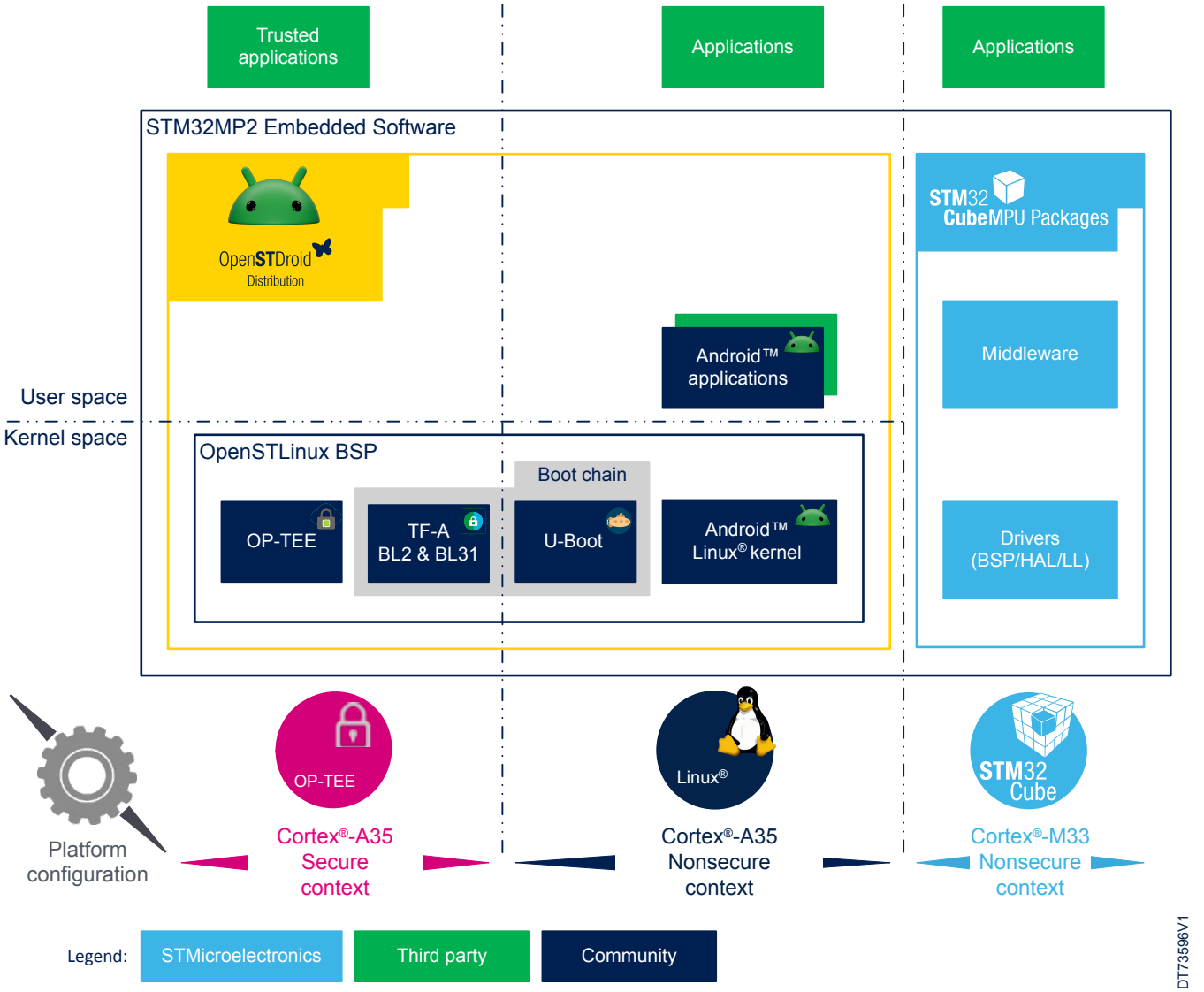
STM32MP2 OpenSTDroid Starter Package



Product status link
STM32MP2DroidSta

Features

- STM32MP2 OpenSTDroid Starter Package for Android™, featuring the OpenSTDroid Distribution:
  - OpenSTLinux board support package (BSP):
    - Secure boot chain
    - Secure OS
    - Linux® kernel running on the Arm® Cortex®-A processor
  - Android™ application frameworks (middleware):
    - Provide APIs through the OpenSTLinux BSP to the applications
    - Typically for user interaction via the display or the touch panel
- Firmware running on the Arm® Cortex®-M processor:
  - STM32CubeMP2 MPU Package in nonsecure mode:
    - Based on HAL drivers and middleware, similar to those for STM32 microcontrollers
    - Completed with coprocessor management for interaction with the Arm® Cortex®-A processor

Description

The STM32MP2DroidSta OpenSTDroid Starter Package provides the software image for the STM32MP2 embedded software distribution for Android™.

STM32MP2DroidSta includes the OpenSTDroid Distribution binaries and the partition layout required to program the device with STM32CubeProgrammer (STM32CubeProg). The STM32CubeProgrammer tool is used to install this image on the STM32MP25xx-based evaluation board.

1 General information

The STM32MP2DroidSta OpenSTDroid Starter Package is based on the Android™ build framework. It runs on STM32MP2 microprocessors featuring Arm® Cortex® processors.

Note: Android is a trademark of Google LLC.

Arm is a registered trademark of Arm Limited (or its subsidiaries) in the US and/or elsewhere.

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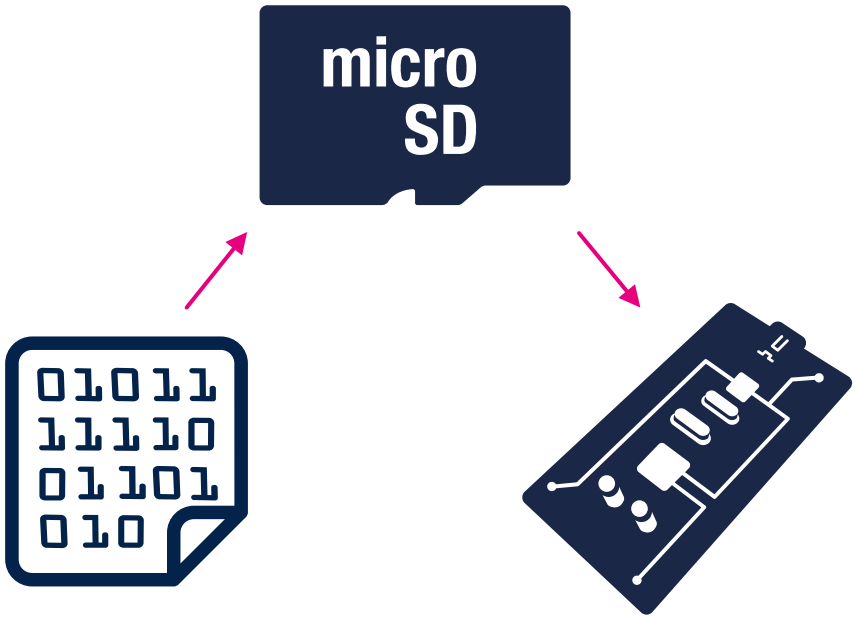
Figure 1 shows the usage of the Starter Package embedded software.

Figure 1. STM32MP2 Starter Package embedded software



DT73598V1

1.1 Ordering information

STM32MP2DroidSta is available for free download from the *www.st.com* website.

1.2 Versioning

The major and minor versions of the STM32MP2DroidSta OpenSTDroid Starter Package are aligned on the major and minor versions of the OpenSTLinux Distribution. This prevents painful backward compatibility attempts and makes dependencies straightforward.

The STM32MP2DroidSta generic versioning vx.y.z is built as follows:

- **x**: major version matching the OpenSTLinux Distribution major version. Each new major version is incompatible with previous OpenSTLinux Distribution versions.
- **y**: minor version matching the OpenSTLinux Distribution minor version. Each new minor version might be incompatible with previous OpenSTLinux Distribution versions.
- **z**: patch version to introduce bug fixes. A patch version is implemented in a backward-compatible manner.

1.3 License

STM32MP2DroidSta is delivered under the *Mix Ultimate Liberty+OSS+3rd-party V1* software license agreement (SLA0048).

Software component license agreements

The software components provided in this package come with different license schemes. Refer to wiki.st.com/stm32mpu/wiki/STM32MP2DroidSta_licenses for details.

Revision history

Table 1. **Document revision history**

Date	Revision	Changes
08-Nov-2024	1	Initial release.

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